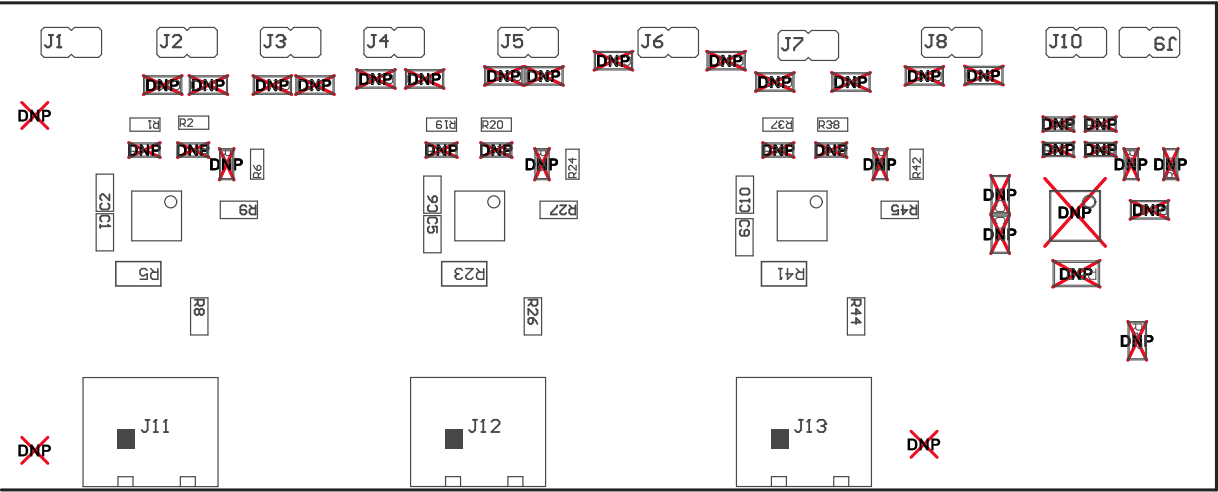
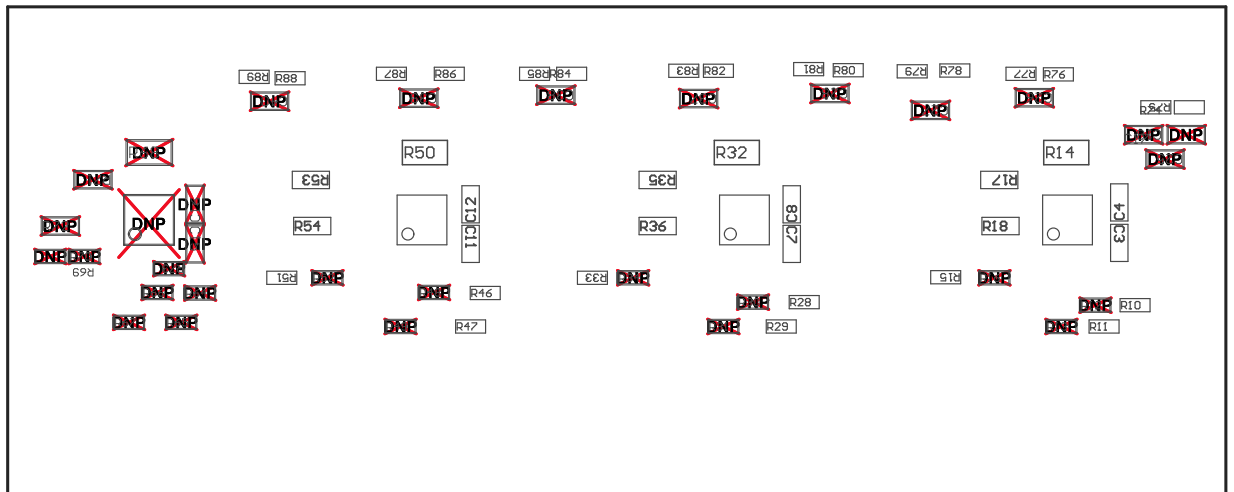


- ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

|                                  |                                   |                   |                                |
|----------------------------------|-----------------------------------|-------------------|--------------------------------|
| PCB VIEWED FROM TOP SIDE         | BOARD #: TIDA - 1467              | REV: E1           | SUN REV: Not In VersionControl |
|                                  | TID #: TIDA-01467                 |                   |                                |
| PLOT NAME = Top Assembly Drawing | GENERATED : 7/17/2017 10:26:35 AM | TEXAS INSTRUMENTS |                                |



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